

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

3743

Applicant: Thomas J Fitzgerald et al.

Title: DEVICE AND METHOD FOR PACKAGE WARP COMPENSATION IN AN INTEGRATED HEAT SPREADER

Docket No.: 884.A12US1

Filed: December 21, 2001

Examiner: Unknown

Customer No.: 21186

Serial No.: 10/023720

Due Date: N/A

Group Art Unit: 3743

Confirmation No.: 6808

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We are transmitting herewith the following attached items (as indicated with an "X"):

☒ A return postcard.

☒ An Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 4 cited documents.

☒ Revocation and Power of Attorney Certificate Under 3.73(b) (2 pgs.).

☒ Status Inquiry (1 pg.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

Alexandria, VA 22313-1450

By: Ann M. McCrackin
Atty: Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 13 day of November, 2003.

KACIA LEE
Name: Kacia Lee

Kacia Lee
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)

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S/N 10/023720

PATENT

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Applicant:	Thomas J Fitzgerald et al.	Examiner:	Unknown
Serial No.:	10/023720	Group Art Unit:	3743
Filed:	December 21, 2001	Docket:	884.A12US1
Title:	DEVICE AND METHOD FOR PACKAGE WARP COMPENSATION IN AN INTEGRATED HEAT SPREADER		
Assignee:	Intel Corporation	Customer No.:	21186

INFORMATION DISCLOSURE STATEMENT

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In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(1) and 37 C.F.R. §1.97(e)(1), Applicants state that each item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Supplemental Information Disclosure Statement. A copy of the relevant International Search Report, in PCT/US02/36039, mailed August 28, 2003, is enclosed.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

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INFORMATION DISCLOSURE STATEMENT

Serial No :10/023720

Filing Date: December 21, 2001

Title: DEVICE AND METHOD FOR PACKAGE WARP COMPENSATION IN AN INTEGRATED HEAT SPREADER

Assignee: Intel Corporation

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Dkt: 884.A12US1 (INTEL)

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

THOMAS J FITZGERALD ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, Minnesota 55402
612-349-9592

Date Nov. 13, 2003

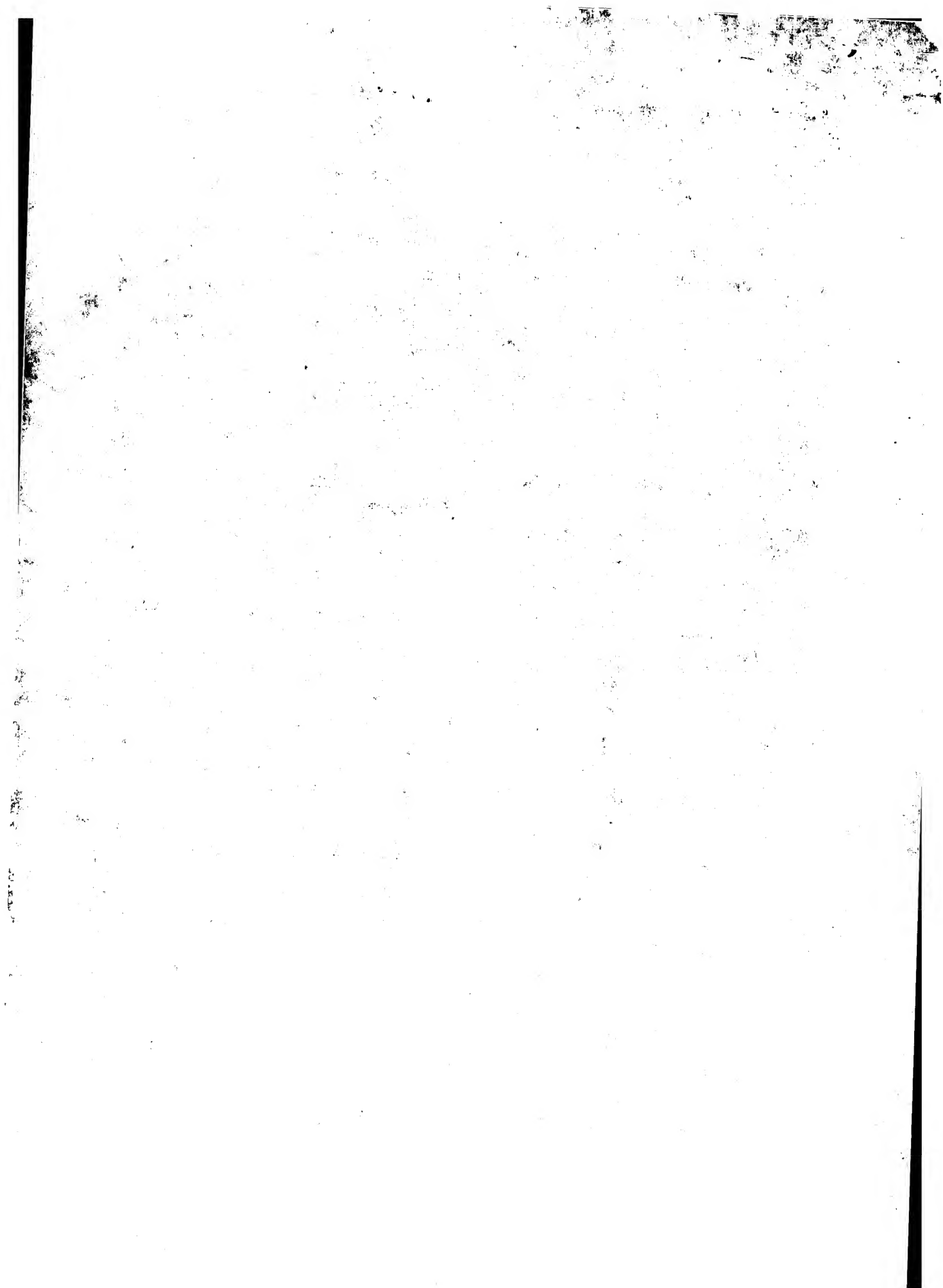
By Ann M. McCrackin

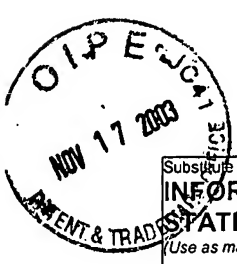
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KACIA LEE
Name

Kacia Lee
Signature





Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	<i>Complete if Known</i>	
	Application Number	10/023720
	Filing Date	December 21, 2001
	First Named Inventor	Fitzgerald, Thomas
	Group Art Unit	3743
	Examiner Name	Unknown
Sheet 1 of 1		Attorney Docket No: 884.A12US1

US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-6,139,975	10/31/2000	Mawatari, O., et al.	428	600	01/26/1999

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		KELLY, G. , et al., "Accurate Prediction of PQFP Warpage", <u>IEEE Proceedings of the Electronic Components and Technology Conference</u> , 44, Washington, (1994), 102-106	
		METROL, A., "Stress Analysis and Thermal Characterization of a High Pin Count PQFP", <u>Transactions of the ASME: Journal of Electronic Packaging</u> , 114, (1992), 211-220	
		ZHANG, X., et al., "Thermo-Mechanical Analysis for a Multi Chip Build Up Substrate Based Package", <u>Proceedings of the 2001 8th International Symposium on the Physical and Failure Analysis of Integrated Circuits. IPFA 2001 (Cat. No 01TH8548)</u> , (2001), 67-72	

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